Announcement and Call for Abstracts
Topical Workshop on
Interposers, 3D IC & Packaging

This workshop is being held as a part of the Device Packaging Conference

WeKoPa Resort & Casino
Fountain Hills, Arizona - USA
March 5 - 8, 2018

Technical Chair:	Technical Co-Chair:	Technical Co-Chair:
Lars Boettcher, Fraunhofer IZM lars.boettcher@izm.fraunhofer.de	**Rahul Agarwal**, AMD Rahul.Agarwal@amd.com	**Rama Puligadda,** Brewer Science rpuligadda@brewerscience.com

Interposers, 3D IC & Packaging Organizing Committee:

Severine Cheramy, CEA Leti
Phil Garrou, Micro. Consultants of NC
Yann Guillou, Unity SC
Inho Lee, Dow Electronic Materials
Cheng-Ta Ko, Unimicron
Diane Scheele, Versum Materials (Dynaloy-Eastman)

Interposers, 3D IC & Packaging Workshop Focus:

The objective of this Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who have been working in the area of Advanced 3D Packaging. This workshop has been specifically organized to allow for the presentation and debate of some of the latest advancements in Advanced 3D technologies as well as to bridge the gap between the back-end wafer-level 3D integration and 3D packaging, covering wire-bonded chip stack, interposers, package-on-package (PoP), through-silicon-via (TSV) based die-to-die (or chip), die-to-wafer, and wafer-to-wafer 3D approaches.

Abstracts are being requested on the following topics:

- *Advanced Stacked Dies Technology*
- *Advanced Stacked Packages*
- *PWB Embedded Device Technologies*
- *Stacked Memories*
- *Silicon Interposers & Glass Interposers*
- *High Density Interposers & Integrated Passives*
- *Folded Flex*
- *Through Silicon Vias (TSV) Technologies*
- *Vertical Interconnects*
- *Hybrid bonding*
- *Advanced 3D Materials and Processes*
- *Advanced 3D Testing and Probing Challenges*
- *Failure Analysis and Reliability*
- *Simulation and Modeling*
- *Applications and System Requirements*
- *Thermal Management*
- *Thin Wafer Handling and Processing*
- *Cost Considerations for 2.5 & 3D Packaging*

Those wishing to present in the Device Packaging Conference must submit a 300-500 word abstract electronically **no later than November 8, 2017**, using the on-line submittal form at: www.imaps.org/abstracts.htm. No formal technical paper is required. A reproduction-ready two- to four-page concise summary with text (figures and graphs included if necessary) will be required for the abstract booklet on January 19, 2018. A post-conference DOWNLOAD containing the full presentation material as supplied by authors will be emailed following the Conference to all attendees. Please contact Brian Schieman by email at bschieman@imaps.org if you have questions. ***STUDENT AUTHORS***: upon abstract submission, please select "**yes, I'm a full-time student**" on the form and you will automatically be entered in the student competition with *$3000 in foundation awards ($1500 1st, $1000 2nd, $500 3rd).*

Device Packaging Exhibit and Technology Show:

IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of **Interposers, 3D IC & Packaging**. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8' by 10' exhibit spaces will be available. ***NOW SOLD OUT!*** Contact Brian Schieman by email at bschieman@imaps.org.

Device Packaging Professional Development Courses (PDCs):

For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 5th, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course on-line at www.imaps.org/pdc **no later than November 8, 2017.**